

ABSTRACT

A design support apparatus for semiconductor devices that supports wiring design for bond wires that connect a semiconductor chip and an interposer is provided. The
5 design support apparatus for semiconductor devices includes a unit that creates simulated design data simulating occurrence of fluctuation in an arrangement position of a semiconductor chip on an interposer and occurrence of fluctuation in bond wire connection terminal positions of
10 the interposer. The design support apparatus for semiconductor devices also includes an analyzing unit that analyzes, based on the simulated design data, deficiencies in manufacturing of semiconductor devices due to the fluctuation in the arrangement position of the
15 semiconductor chip on the interposer and the fluctuation in the bond wire connection terminal positions of the interposer.